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Intel - 5SGXEBBR3H43C2N Datasheet



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Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Details	
Product Status	Obsolete
Number of LABs/CLBs	359200
Number of Logic Elements/Cells	952000
Total RAM Bits	53248000
Number of I/O	600
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1760-BBGA, FCBGA
Supplier Device Package	1760-HBGA (45x45)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxebbr3h43c2n

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This section lists the functional operating limits for the AC and DC parameters for Stratix V devices. Table 6 lists the steady-state voltage and current values expected from Stratix V devices. Power supply ramps must all be strictly monotonic, without plateaus.

Table 6. Recommended Operating Conditions for Stratix V Devices (Part 1 of 2)

Symbol	Description	Condition	Min ⁽⁴⁾	Тур	Max ⁽⁴⁾	Unit
	Core voltage and periphery circuitry power supply (C1, C2, I2, and I3YY speed grades)	_	0.87	0.9	0.93	V
V _{CC}	Core voltage and periphery circuitry power supply (C2L, C3, C4, I2L, I3, I3L, and I4 speed grades) ⁽³⁾		0.82	0.85	0.88	V
V _{CCPT}	Power supply for programmable power technology	_	1.45	1.50	1.55	V
V _{CC_AUX}	Auxiliary supply for the programmable power technology	_	2.375	2.5	2.625	V
VI (1)	I/O pre-driver (3.0 V) power supply	_	2.85	3.0	3.15	V
V _{CCPD} ⁽¹⁾	I/O pre-driver (2.5 V) power supply	_	2.375	2.5	2.625	V
	I/O buffers (3.0 V) power supply		2.85	3.0	3.15	V
	I/O buffers (2.5 V) power supply	_	2.375	2.5	2.625	V
	I/O buffers (1.8 V) power supply		1.71	1.8	1.89	V
V _{CCIO}	I/O buffers (1.5 V) power supply	_	1.425	1.5	1.575	V
	I/O buffers (1.35 V) power supply	_	1.283	1.35	1.45	V
	I/O buffers (1.25 V) power supply	_	1.19	1.25	1.31	V
	I/O buffers (1.2 V) power supply	_	1.14	1.2	1.26	V
	Configuration pins (3.0 V) power supply	_	2.85	3.0	3.15	V
V _{CCPGM}	Configuration pins (2.5 V) power supply	_	2.375	2.5	2.625	V
	Configuration pins (1.8 V) power supply	_	1.71	1.8	1.89	V
V _{CCA_FPLL}	PLL analog voltage regulator power supply	_	2.375	2.5	2.625	V
V _{CCD_FPLL}	PLL digital voltage regulator power supply	_	1.45	1.5	1.55	V
V _{CCBAT} (2)	Battery back-up power supply (For design security volatile key register)	_	1.2	_	3.0	V
VI	DC input voltage	_	-0.5	_	3.6	V
V ₀	Output voltage	—	0	—	V _{CCIO}	V
т	Operating junction temperature	Commercial	0	—	85	°C
TJ	Operating junction temperature	Industrial	-40	_	100	°C

Symbol	Description	Devices	Minimum ⁽⁴⁾	Typical	Maximum ⁽⁴⁾	Unit
			0.82	0.85	0.88	
V _{CCR_GXBR}	Receiver analog power supply (right side)	GX, GS, GT	0.87	0.90	0.93	v
(2)	Receiver analog power supply (right side)	un, us, ui	0.97	1.0	1.03	v
			1.03	1.05	1.07	
V _{CCR_GTBR}	Receiver analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
			0.82	0.85	0.88	
V _{CCT_GXBL}	Transmitter analog power supply (left side)	GX, GS, GT	0.87	0.90	0.93	V
	Transmitter analog power supply (left side)		0.97	1.0	1.03	
			1.03	1.05	1.07	
		GX, GS, GT	0.82	0.85	0.88	V
V _{CCT_GXBR}	Transmitter analog nower supply (right side)		0.87	0.90	0.93	
(2)	Transmitter analog power supply (right side)		0.97	1.0	1.03	
			1.03	1.05	1.07	
V _{CCT_GTBR}	Transmitter analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
V_{CCL_GTBR}	Transmitter clock network power supply	GT	1.02	1.05	1.08	V
V _{CCH_GXBL}	Transmitter output buffer power supply (left side)	GX, GS, GT	1.425	1.5	1.575	V
V _{CCH_GXBR}	Transmitter output buffer power supply (right side)	GX, GS, GT	1.425	1.5	1.575	V

Table 7.	Recommended Transceiver Power Supply Operating Conditions for Stratix V GX,	GS, and GT Devices
(Part 2	of 2)	

Notes to Table 7:

(1) This supply must be connected to 3.0 V if the CMU PLL, receiver CDR, or both, are configured at a base data rate > 6.5 Gbps. Up to 6.5 Gbps, you can connect this supply to either 3.0 V or 2.5 V.

(2) Refer to Table 8 to select the correct power supply level for your design.

(3) When using ATX PLLs, the supply must be 3.0 V.

(4) This value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

			Resistance Tolerance					
Symbol	Description	Conditions	C1	C2,I2	C3, I3, I3YY	C4, I4	Unit	
50-Ω R _S	Internal series termination without calibration (50- Ω setting)	$V_{CCIO} = 1.8$ and 1.5 V	±30	±30	±40	±40	%	
50-Ω R _S	Internal series termination without calibration (50- Ω setting)	V _{CCI0} = 1.2 V	±35	±35	±50	±50	%	
100-Ω R _D	Internal differential termination (100- Ω setting)	V _{CCPD} = 2.5 V	±25	±25	±25	±25	%	

Table 12. OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices (Part 2 of 2)

Calibration accuracy for the calibrated series and parallel OCTs are applicable at the moment of calibration. When voltage and temperature conditions change after calibration, the tolerance may change.

OCT calibration is automatically performed at power-up for OCT-enabled I/Os. Table 13 lists the OCT variation with temperature and voltage after power-up calibration. Use Table 13 to determine the OCT variation after power-up calibration and Equation 1 to determine the OCT variation without recalibration.

Equation 1. OCT Variation Without Recalibration for Stratix V Devices (1), (2), (3), (4), (5), (6)

$$R_{OCT} \,=\, R_{SCAL} \Big(1 + \langle \frac{dR}{dT} \times \Delta T \rangle \pm \langle \frac{dR}{dV} \times \Delta V \rangle \Big)$$

Notes to Equation 1:

- (1) The R_{OCT} value shows the range of OCT resistance with the variation of temperature and V_{CCIO} .
- (2) R_{SCAL} is the OCT resistance value at power-up.
- (3) ΔT is the variation of temperature with respect to the temperature at power-up.
- (4) ΔV is the variation of voltage with respect to the V_{CCIO} at power-up.
- (5) dR/dT is the percentage change of R_{SCAL} with temperature.
- (6) dR/dV is the percentage change of $\mathsf{R}_{\mathsf{SCAL}}$ with voltage.

Table 13 lists the on-chip termination variation after power-up calibration.

Table 13.	OCT Variation after Power-U	Calibration for Stratix V Devices	(Part 1 of 2) ⁽¹⁾
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Symbol	Description	V _{CCIO} (V)	Typical	Unit
		3.0	0.0297	
	OCT variation with voltage without recalibration	2.5	0.0344	
dR/dV		1.8	0.0499	%/mV
		1.5	0.0744	
		1.2	0.1241	

Internal Weak Pull-Up Resistor

Table 16 lists the weak pull-up resistor values for Stratix V devices.

Symbol	Description	V _{CCIO} Conditions (V) ⁽³⁾	Value ⁽⁴⁾	Unit
		3.0 ±5%	25	kΩ
		2.5 ±5% 25		
	Value of the I/O pin pull-up resistor before	1.8 ±5%	25	kΩ
R _{PU}	and during configuration, as well as user mode if you enable the programmable	1.5 ±5%	25	kΩ
	pull-up resistor option.	1.35 ±5%	25	kΩ
		1.25 ±5%	25	kΩ
		1.2 ±5%	25	kΩ

Table 16. Internal Weak Pull-Up Resistor for Stratix V Devices (1), (2)

Notes to Table 16:

(1) All I/O pins have an option to enable the weak pull-up resistor except the configuration, test, and JTAG pins.

(2) The internal weak pull-down feature is only available for the JTAG TCK pin. The typical value for this internal weak pull-down resistor is approximately 25 k Ω .

- (3) The pin pull-up resistance values may be lower if an external source drives the pin higher than V_{CCIO}.
- (4) These specifications are valid with a $\pm 10\%$ tolerance to cover changes over PVT.

I/O Standard Specifications

Table 17 through Table 22 list the input voltage (V_{IH} and V_{IL}), output voltage (V_{OH} and V_{OL}), and current drive characteristics (I_{OH} and I_{OL}) for various I/O standards supported by Stratix V devices. These tables also show the Stratix V device family I/O standard specifications. The V_{OL} and V_{OH} values are valid at the corresponding I_{OH} and I_{OL}, respectively.

For an explanation of the terms used in Table 17 through Table 22, refer to "Glossary" on page 65. For tolerance calculations across all SSTL and HSTL I/O standards, refer to Altera knowledge base solution rd07262012_486.

I/O	V _{CCIO} (V)		V _{CCIO} (V)		V _{IL} (V)		(V)	V _{OL} (V)	V _{OH} (V)	IOL	I _{oh}
Standard	Min	Тур	Max	Min	Max	Min	Max	Max	Min	(mĀ)	(mÅ)
LVTTL	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.4	2.4	2	-2
LVCMOS	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.2	$V_{CCI0} - 0.2$	0.1	-0.1
2.5 V	2.375	2.5	2.625	-0.3	0.7	1.7	3.6	0.4	2	1	-1
1.8 V	1.71	1.8	1.89	-0.3	0.35 * V _{CCI0}	0.65 * V _{CCI0}	V _{CCI0} + 0.3	0.45	V _{CCI0} – 0.45	2	-2
1.5 V	1.425	1.5	1.575	-0.3	0.35 * V _{CCI0}	0.65 * V _{CCI0}	V _{CCI0} + 0.3	0.25 * V _{CCI0}	0.75 * V _{CCIO}	2	-2
1.2 V	1.14	1.2	1.26	-0.3	0.35 * V _{CCI0}	0.65 * V _{CCIO}	V _{CCI0} + 0.3	0.25 * V _{CCI0}	0.75 * V _{CCI0}	2	-2

Table 17. Single-Ended I/O Standards for Stratix V Devices

- You typically use the interactive Excel-based Early Power Estimator before designing the FPGA to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.
- ***** For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

Symbol/	Conditions	Trai	nsceive Grade	r Speed 1	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Reconfiguration clock (mgmt_clk_clk) frequency	_	100	_	125	100		125	100		125	MHz
Receiver											
Supported I/O Standards	_			1.4-V PCM	L, 1.5-V	PCML,	2.5-V PCM	L, LVPE	CL, and	d LVDS	
Data rate (Standard PCS) (9), (23)	_	600	_	12200	600	_	12200	600	_	8500/ 10312.5 (24)	Mbps
Data rate (10G PCS) ^{(9),} ⁽²³⁾		600	_	14100	600	_	12500	600	_	8500/ 10312.5 (24)	Mbps
Absolute V_{MAX} for a receiver pin (5)		_	_	1.2	—	_	1.2	—	_	1.2	V
Absolute V _{MIN} for a receiver pin	_	-0.4	_		-0.4	_	_	-0.4	_	_	V
Maximum peak- to-peak differential input voltage V _{ID} (diff p- p) before device configuration ⁽²²⁾	_	_	_	1.6	_	_	1.6	_	_	1.6	V
Maximum peak- to-peak	V _{CCR_GXB} = 1.0 V/1.05 V (V _{ICM} = 0.70 V)	_	_	2.0	_	_	2.0	_	_	2.0	V
differential input voltage V_{ID} (diff p- p) after device configuration ⁽¹⁸⁾ ,	$V_{CCR_GXB} = 0.90 V$ (V _{ICM} = 0.6 V)	_	_	2.4	_	_	2.4	_	_	2.4	V
(22)	$V_{CCR_GXB} = 0.85 V$ (V _{ICM} = 0.6 V)			2.4			2.4			2.4	V
Minimum differential eye opening at receiver serial input pins ^{(6), (22),} (27)	_	85		_	85		_	85	_	_	mV

Table 23. Transceiver Specifications for Stratix V GX and GS Devices ⁽¹⁾ (Part 3 of 7)

Symbol/	Conditions	Tra	nsceive Grade	r Speed 1	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
	DC Gain Setting = 0		0	_	_	0		_	0	_	dB
	DC Gain Setting = 1	_	2	_	—	2	_	_	2	_	dB
Programmable DC gain	DC Gain Setting = 2	_	4	_	_	4	_	_	4	_	dB
	DC Gain Setting = 3	_	6	_	_	6	_	_	6	_	dB
	DC Gain Setting = 4	_	8	_	_	8	_	_	8	—	dB
Transmitter											
Supported I/O Standards	_		1.4-V and 1.5-V PCML								
Data rate (Standard PCS)	_	600	_	12200	600	_	12200	600	_	8500/ 10312.5 (24)	Mbps
Data rate (10G PCS)	_	600	_	14100	600		12500	600		8500/ 10312.5 (24)	Mbps
	85-Ω setting		85 ± 20%	_	_	85 ± 20%		_	85 ± 20%	_	Ω
Differential on-	100-Ω setting	_	100 ± 20%	_	_	100 ± 20%	_	_	100 ± 20%	_	Ω
chip termination resistors	120-Ω setting	_	120 ± 20%			120 ± 20%		_	120 ± 20%		Ω
	150-Ω setting		150 ± 20%			150 ± 20%			150 ± 20%		Ω
V _{OCM} (AC coupled)	0.65-V setting		650		_	650		_	650	_	mV
V _{OCM} (DC coupled)	_		650		_	650		_	650	_	mV
Rise time (7)	20% to 80%	30		160	30		160	30		160	ps
Fall time ⁽⁷⁾	80% to 20%	30		160	30		160	30		160	ps
Intra-differential pair skew	Tx V _{CM} = 0.5 V and slew rate of 15 ps			15			15			15	ps
Intra-transceiver block transmitter channel-to- channel skew	x6 PMA bonded mode			120			120			120	ps

Table 23. Transceiver Specifications for Stratix V GX and GS Devices ⁽¹⁾ (Part 5 of 7)

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 2 of 5)⁽¹⁾

Symbol/	Conditions		Transceive Speed Grade			Fransceive Deed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	Ī
	100 Hz			-70			-70	
Transmitter REFCLK	1 kHz		_	-90	_	_	-90	-
Phase Noise (622	10 kHz		_	-100	_	_	-100	dBc/Hz
MHz) ⁽¹⁸⁾	100 kHz		—	-110	_	—	-110	
	\geq 1 MHz		—	-120	_	—	-120	-
Transmitter REFCLK Phase Jitter (100 MHz) ⁽¹⁵⁾	10 kHz to 1.5 MHz (PCIe)		_	3	_		3	ps (rms)
RREF ⁽¹⁷⁾	—		1800 ± 1%	_	_	1800 ± 1%	_	Ω
Transceiver Clocks								
fixedclk clock frequency	PCIe Receiver Detect		100 or 125	_	_	100 or 125	_	MHz
Reconfiguration clock (mgmt_clk_clk) frequency	_	100	_	125	100	_	125	MHz
Receiver				•				
Supported I/O Standards	—		1.4-V PCMI	_, 1.5-V PCM	L, 2.5-V PCI	ML, LVPEC	L, and LVDS	3
Data rate (Standard PCS) ⁽²¹⁾	GX channels	600	_	8500	600	_	8500	Mbps
Data rate (10G PCS) ⁽²¹⁾	GX channels	600	_	12,500	600	_	12,500	Mbps
Data rate	GT channels	19,600	—	28,050	19,600	—	25,780	Mbps
Absolute V _{MAX} for a receiver pin ⁽³⁾	GT channels	_	_	1.2	_	_	1.2	V
Absolute V _{MIN} for a receiver pin	GT channels	-0.4	_	_	-0.4		_	V
Maximum peak-to-peak	GT channels	_	—	1.6	—	—	1.6	V
differential input voltage V _{ID} (diff p-p) before device configuration ⁽²⁰⁾	GX channels				(8)			
	GT channels							
Maximum peak-to-peak differential input voltage V_{ID} (diff p-p) after device configuration (¹⁶), (²⁰)	V _{CCR_GTB} = 1.05 V (V _{ICM} = 0.65 V)	—	-	2.2	_	_	2.2	V
oomguration (), ()	GX channels		•	•	(8)			
Minimum differential	GT channels	200	_		200			mV
eye opening at receiver serial input pins ⁽⁴⁾ , ⁽²⁰⁾	GX channels				(8)			

Figure 6 shows the Stratix V DC gain curves for GT channels.

Figure 6. DC Gain Curves for GT Channels

Transceiver Characterization

This section summarizes the Stratix V transceiver characterization results for compliance with the following protocols:

- Interlaken
- 40G (XLAUI)/100G (CAUI)
- 10GBase-KR
- QSGMII
- XAUI
- SFI
- Gigabit Ethernet (Gbe / GIGE)
- SPAUI
- Serial Rapid IO (SRIO)
- CPRI
- OBSAI
- Hyper Transport (HT)
- SATA
- SAS
- CEI

PLL Specifications

Table 31 lists the Stratix V PLL specifications when operating in both the commercial junction temperature range (0° to 85° C) and the industrial junction temperature range (-40° to 100° C).

Table 31. PLL Specifications for Stratix V Devices (Part 1 of 3)

Symbol	Parameter	Min	Тур	Max	Unit
	Input clock frequency (C1, C2, C2L, I2, and I2L speed grades)	5	_	800 (1)	MHz
f _{IN}	Input clock frequency (C3, I3, I3L, and I3YY speed grades)	5	_	800 (1)	MHz
	Input clock frequency (C4, I4 speed grades)	5	_	650 ⁽¹⁾	MHz
f _{INPFD}	Input frequency to the PFD	5	—	325	MHz
f _{finpfd}	Fractional Input clock frequency to the PFD	50	—	160	MHz
	PLL VCO operating range (C1, C2, C2L, I2, I2L speed grades)	600	_	1600	MHz
f _{VCO}	PLL VCO operating range (C3, I3, I3L, I3YY speed grades)	600	_	1600	MHz
	PLL VCO operating range (C4, I4 speed grades)	600	—	1300	MHz MHz MHz MHz MHz MHz
t _{einduty}	Input clock or external feedback clock input duty cycle	40		60	%
	Output frequency for an internal global or regional clock (C1, C2, C2L, I2, I2L speed grades)	—	_	717 ⁽²⁾	MHz
f _{out}	Output frequency for an internal global or regional clock (C3, I3, I3L speed grades)	_	_	650 ⁽²⁾	MHz
	Output frequency for an internal global or regional clock (C4, I4 speed grades)	_	_	580 ⁽²⁾	MHz
f _{out_ext}	Output frequency for an external clock output (C1, C2, C2L, I2, I2L speed grades)	_	_	800 (2)	MHz
	Output frequency for an external clock output (C3, I3, I3L speed grades)	_	_	667 ⁽²⁾	MHz
	Output frequency for an external clock output (C4, I4 speed grades)	_	_	553 ⁽²⁾	MHz
t _{outduty}	Duty cycle for a dedicated external clock output (when set to 50%)	45	50	55	%
t _{FCOMP}	External feedback clock compensation time	_	—	10	ns
f _{dyconfigclk}	Dynamic Configuration Clock used for <code>mgmt_clk</code> and <code>scanclk</code>	_	_	100	MHz
t _{LOCK}	Time required to lock from the end-of-device configuration or deassertion of areset	_	_	1	ms
t _{olock}	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)	_	_	1	ms
	PLL closed-loop low bandwidth		0.3	—	MHz
f _{CLBW}	PLL closed-loop medium bandwidth	_	1.5		MHz
	PLL closed-loop high bandwidth (7)		4	—	MHz
t _{PLL_PSERR}	Accuracy of PLL phase shift			±50	ps
t _{areset}	Minimum pulse width on the areset signal	10	_		ns

Family	Device	Package	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits) ^{(4), (5)}
Stratix V E ⁽¹⁾	5SEE9	—	342,742,976	700,888
	5SEEB	_	342,742,976	700,888

Table 47. Uncompressed .rbf Sizes for Stratix V Devices

Notes to Table 47:

(1) Stratix V E devices do not have PCI Express® (PCIe®) hard IP. Stratix V E devices do not support the CvP configuration scheme.

(2) 36-transceiver devices.

(3) 24-transceiver devices.

(4) File size for the periphery image.

(5) The IOCSR .rbf size is specifically for the CvP feature.

Use the data in Table 47 to estimate the file size before design compilation. Different configuration file formats, such as a hexadecimal (.hex) or tabular text file (.ttf) format, have different file sizes. For the different types of configuration file and file sizes, refer to the Quartus II software. However, for a specific version of the Quartus II software, any design targeted for the same device has the same uncompressed configuration file size. If you are using compression, the file size can vary after each compilation because the compression ratio depends on your design.

• For more information about setting device configuration options, refer to *Configuration, Design Security, and Remote System Upgrades in Stratix V Devices.* For creating configuration files, refer to the *Quartus II Help.*

Table 48 lists the minimum configuration time estimates for Stratix V devices.

	Member		Active Serial ⁽¹⁾		Fast Passive Parallel ⁽²⁾			
Variant	Member Code	Width	DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)	
	A3	4	100	0.534	32	100	0.067	
	AS	4	100	0.344	32	100	0.043	
	A4	4	100	0.534	32	100	0.067	
	A5	4	100	0.675	32	100	0.084	
	A7	4	100	0.675	32	100	0.084	
GX	A9	4	100	0.857	32	100	0.107	
	AB	4	100	0.857	32	100	0.107	
	B5	4	100	0.676	32	100	0.085	
	B6	4	100	0.676	32	100	0.085	
	B9	4	100	0.857	32	100	0.107	
	BB	4	100	0.857	32	100	0.107	
ст	C5	4	100	0.675	32	100	0.084	
GT	C7	4	100	0.675	32	100	0.084	

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
	Disabled	Disabled	1
FPP ×32	Disabled	Enabled	4
FFF X02	Enabled	Disabled	8
	Enabled	Enabled	8

Note to Table 49:

(1) Depending on the DCLK-to-DATA [] ratio, the host must send a DCLK frequency that is r times the data rate in bytes per second (Bps), or words per second (Wps). For example, in FPP ×16 when the DCLK-to-DATA [] ratio is 2, the DCLK frequency must be 2 times the data rate in Wps. Stratix V devices use the additional clock cycles to decrypt and decompress the configuration data.

Figure 11 shows the configuration interface connections between the Stratix V device and a MAX II or MAX V device for single device configuration.

Figure 11. Single Device FPP Configuration Using an External Host



Notes to Figure 11:

- (1) Connect the resistor to a supply that provides an acceptable input signal for the Stratix V device. V_{CCPGM} must be high enough to meet the V_{IH} specification of the I/O on the device and the external host. Altera recommends powering up all configuration system I/Os with V_{CCPGM} .
- (2) You can leave the nCEO pin unconnected or use it as a user I/O pin when it does not feed another device's nCE pin.
- (3) The MSEL pin settings vary for different data width, configuration voltage standards, and POR delay. To connect MSEL, refer to the MSEL Pin Settings section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (4) If you use FPP ×8, use DATA [7..0]. If you use FPP ×16, use DATA [15..0].

IF the DCLK-to-DATA[] ratio is greater than 1, at the end of configuration, you can only stop the DCLK (DCLK-to-DATA[] ratio – 1) clock cycles after the last data is latched into the Stratix V device.

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Table 51 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA[] ratio is more than 1.

Symbol	Parameter	Minimum	Maximum	Units
t _{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t _{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t _{CFG}	nCONFIG low pulse width	2	_	μS
t _{STATUS}	nSTATUS low pulse width	268	1,506 ⁽²⁾	μS
t _{CF2ST1}	nCONFIG high to nSTATUS high	—	1,506 ⁽²⁾	μS
t _{CF2CK} ⁽⁵⁾	nCONFIG high to first rising edge on DCLK	1,506	_	μS
t _{ST2CK} ⁽⁵⁾	nSTATUS high to first rising edge of DCLK	2	—	μS
t _{DSU}	DATA [] setup time before rising edge on DCLK	5.5		ns
t _{DH}	DATA [] hold time after rising edge on DCLK	N-1/f _{DCLK} ⁽⁵⁾		S
t _{CH}	DCLK high time	$0.45 imes 1/f_{MAX}$		S
t _{CL}	DCLK low time	$0.45\times1/f_{MAX}$		S
t _{CLK}	DCLK period	1/f _{MAX}		S
f	DCLK frequency (FPP ×8/×16)	—	125	MHz
f _{MAX}	DCLK frequency (FPP ×32)	—	100	MHz
t _R	Input rise time	—	40	ns
t _F	Input fall time	—	40	ns
t _{CD2UM}	CONF_DONE high to user mode ⁽³⁾	175	437	μS
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t_{CD2CU} + (8576 × CLKUSR period) ⁽⁴⁾	_	_

Notes to Table 51:

- (1) Use these timing parameters when you use the decompression and design security features.
- (2) You can obtain this value if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
- (3) The minimum and maximum numbers apply only if you use the internal oscillator as the clock source for initializing the device.
- (4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (5) N is the ${\tt DCLK}\mbox{-to-DATA}$ ratio and $f_{{\tt DCLK}}$ is the ${\tt DCLK}$ frequency the system is operating.
- (6) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

Table 54 lists the PS configuration timing parameters for Stratix V devices.

Table 54. PS Timing Parameters for Stratix V Devices

Symbol	Parameter	Minimum	Maximum	Units
t _{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t _{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t _{CFG}	nCONFIG low pulse width	2	—	μS
t _{status}	nSTATUS low pulse width	268	1,506 ⁽¹⁾	μS
t _{CF2ST1}	nCONFIG high to nSTATUS high	—	1,506 ⁽²⁾	μS
t _{CF2CK} (5)	nCONFIG high to first rising edge on DCLK	1,506	—	μS
t _{ST2CK} ⁽⁵⁾	nSTATUS high to first rising edge of DCLK	2	—	μS
t _{DSU}	DATA[] setup time before rising edge on DCLK	5.5	—	ns
t _{DH}	DATA[] hold time after rising edge on DCLK	0	—	ns
t _{CH}	DCLK high time	$0.45\times 1/f_{MAX}$	—	S
t _{CL}	DCLK low time	$0.45\times 1/f_{MAX}$	—	S
t _{CLK}	DCLK period	1/f _{MAX}	—	S
f _{MAX}	DCLK frequency	—	125	MHz
t _{CD2UM}	CONF_DONE high to user mode (3)	175	437	μS
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	4 × maximum	
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t_{CD2CU} + (8576 × CLKUSR period) ⁽⁴⁾	_	_

Notes to Table 54:

(1) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.

(2) This value is applicable if you do not delay configuration by externally holding the nSTATUS low.

(3) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.

(4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the "Initialization" section.

(5) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

Initialization

Table 55 lists the initialization clock source option, the applicable configuration schemes, and the maximum frequency.

Table 55. Initialization Clock Source Option and the Maximu	m Frequency
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Initialization Clock Source	Configuration Schemes	Maximum Frequency	Minimum Number of Clock Cycles ⁽¹⁾
Internal Oscillator	AS, PS, FPP	12.5 MHz	
CLKUSR	AS, PS, FPP ⁽²⁾	125 MHz	8576
DCLK	PS, FPP	125 MHz	

Notes to Table 55:

(1) The minimum number of clock cycles required for device initialization.

(2) To enable CLKUSR as the initialization clock source, turn on the Enable user-supplied start-up clock (CLKUSR) option in the Quartus II software from the General panel of the Device and Pin Options dialog box.

Parameter Availa (1) Settin	Availabla	Min	Fast	Model				Slow N	lodel			
	Settings	IITTCOT	Industrial	Commercial	C1	C2	C3	C4	12	13, 13YY	14	Unit
D3	8	0	1.587	1.699	2.793	2.793	2.992	3.192	2.811	3.047	3.257	ns
D4	64	0	0.464	0.492	0.838	0.838	0.924	1.011	0.843	0.920	1.006	ns
D5	64	0	0.464	0.493	0.838	0.838	0.924	1.011	0.844	0.921	1.006	ns
D6	32	0	0.229	0.244	0.415	0.415	0.458	0.503	0.418	0.456	0.499	ns

Notes to Table 58:

(1) You can set this value in the Quartus II software by selecting D1, D2, D3, D5, and D6 in the Assignment Name column of Assignment Editor.

(2) Minimum offset does not include the intrinsic delay.

Programmable Output Buffer Delay

Table 59 lists the delay chain settings that control the rising and falling edge delays of the output buffer. The default delay is 0 ps.

Table 59. Programmable Output Buffer Delay for Stratix V Devices (Table 59.	Programmable Out	put Buffer Delay	y for Stratix V Devices (
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Symbol	Parameter	Typical	Unit
	Rising and/or falling edge delay	0 (default)	ps
D		25	ps
D _{OUTBUF}		50	ps
		75	ps

Note to Table 59:

(1) You can set the programmable output buffer delay in the Quartus II software by setting the Output Buffer Delay Control assignment to either positive, negative, or both edges, with the specific values stated here (in ps) for the Output Buffer Delay assignment.

Glossary

Table 60 lists the glossary for this chapter.

Table 60. Glossary (Part 1 of 4)

Letter	Subject	Definitions
Α		
В	—	—
С		
D	_	—
E		
	f _{HSCLK}	Left and right PLL input clock frequency.
F	f _{HSDR}	High-speed I/O block—Maximum and minimum LVDS data transfer rate (f _{HSDR} = 1/TUI), non-DPA.
	f _{hsdrdpa}	High-speed I/O block—Maximum and minimum LVDS data transfer rate (f _{HSDRDPA} = 1/TUI), DPA.

Table 60. Glossary (Part 2 of 4)

Letter	Subject	Definitions
G		
Н	_	_
Ι		
J	J JTAG Timing Specifications	High-speed I/O block—Deserialization factor (width of parallel data bus). JTAG Timing Specifications: TMS
K L M N O	_	_
Ρ	PLL Specifications	Diagram of PLL Specifications (1)
Q		_
	1	

Letter	Subject	Definitions	
	V _{CM(DC)}	DC common mode input voltage.	
	V _{ICM}	Input common mode voltage—The common mode of the differential signal at the receiver.	
	V _{ID}	Input differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.	
	V _{DIF(AC)}	AC differential input voltage—Minimum AC input differential voltage required for switching.	
	V _{DIF(DC)}	DC differential input voltage— Minimum DC input differential voltage required for switching.	
	V _{IH}	Voltage input high—The minimum positive voltage applied to the input which is accepted by the device as a logic high.	
	V _{IH(AC)}	High-level AC input voltage	
	V _{IH(DC)}	High-level DC input voltage	
V	V _{IL}	Voltage input low—The maximum positive voltage applied to the input which is accepted by the device as a logic low.	
	V _{IL(AC)}	Low-level AC input voltage	
	V _{IL(DC)}	Low-level DC input voltage	
	V _{OCM}	Output common mode voltage—The common mode of the differential signal at the transmitter.	
	V _{OD}	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.	
	V _{SWING}	Differential input voltage	
	V _X	Input differential cross point voltage	
	V _{OX}	Output differential cross point voltage	
W	W	High-speed I/O block—clock boost factor	
X			
Y	_	_	
Z			

Table 60. Glossary (Part 4 of 4)

Table 61. Document Revision History (Part 2 of 3)

Date	Version	Changes
		Added the I3YY speed grade and changed the data rates for the GX channel in Table 1.
		 Added the I3YY speed grade to the V_{CC} description in Table 6.
		 Added the I3YY speed grade to V_{CCHIP_L}, V_{CCHIP_R}, V_{CCHSSI_L}, and V_{CCHSSI_R} descriptions in Table 7.
		■ Added 240-Ω to Table 11.
		Changed CDR PPM tolerance in Table 23.
		 Added additional max data rate for fPLL in Table 23.
		 Added the I3YY speed grade and changed the data rates for transceiver speed grade 3 in Table 25.
		 Added the I3YY speed grade and changed the data rates for transceiver speed grade 3 in Table 26.
		Changed CDR PPM tolerance in Table 28.
		 Added additional max data rate for fPLL in Table 28.
		Changed the mode descriptions for MLAB and M20K in Table 33.
	3.3	• Changed the Max value of f _{HSCLK_OUT} for the C2, C2L, I2, I2L speed grades in Table 36.
November 2014		 Changed the frequency ranges for C1 and C2 in Table 39.
		Changed the .rbf file sizes for 5SGSD6 and 5SGSD8 in Table 47.
		 Added note about nSTATUS to Table 50, Table 51, Table 54.
		 Changed the available settings in Table 58.
		 Changed the note in "Periphery Performance".
		 Updated the "I/O Standard Specifications" section.
		 Updated the "Raw Binary File Size" section.
		 Updated the receiver voltage input range in Table 22.
		 Updated the max frequency for the LVDS clock network in Table 36.
		 Updated the DCLK note to Figure 11.
		 Updated Table 23 VO_{CM} (DC Coupled) condition.
		 Updated Table 6 and Table 7.
		■ Added the DCLK specification to Table 55.
		 Updated the notes for Table 47.
		 Updated the list of parameters for Table 56.
November 2013	3.2	Updated Table 28
November 2013	3.1	Updated Table 33
November 2013	3.0	Updated Table 23 and Table 28
October 2013	2.9	 Updated the "Transceiver Characterization" section
		 Updated Table 3, Table 12, Table 14, Table 19, Table 20, Table 23, Table 24, Table 28, Table 30, Table 31, Table 32, Table 33, Table 36, Table 39, Table 40, Table 41, Table 42, Table 47, Table 53, Table 58, and Table 59
October 2013	2.8	 Added Figure 1 and Figure 3
		 Added the "Transceiver Characterization" section
		 Removed all "Preliminary" designations.

Table 61. Document Revision History (Part 3 of 3)

Date	Version	Changes
		■ Updated Table 2, Table 6, Table 7, Table 20, Table 23, Table 27, Table 47, Table 60
May 2013	2.7	■ Added Table 24, Table 48
		 Updated Figure 9, Figure 10, Figure 11, Figure 12
February 2013	2.6	 Updated Table 7, Table 9, Table 20, Table 23, Table 27, Table 30, Table 31, Table 35, Table 46
		 Updated "Maximum Allowed Overshoot and Undershoot Voltage"
		 Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, Table 27, Table 30, Table 32, Table 35
		Added Table 33
		 Added "Fast Passive Parallel Configuration Timing"
	0.5	 Added "Active Serial Configuration Timing"
December 2012	2.5	 Added "Passive Serial Configuration Timing"
		 Added "Remote System Upgrades"
		 Added "User Watchdog Internal Circuitry Timing Specification"
		 Added "Initialization"
		 Added "Raw Binary File Size"
		 Added Figure 1, Figure 2, and Figure 3.
June 2012	2.4	 Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 27, Table 29, Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 41, Table 43, Table 56, and Table 59.
		 Various edits throughout to fix bugs.
		 Changed title of document to Stratix V Device Datasheet.
		 Removed document from the Stratix V handbook and made it a separate document.
February 2012	2.3	■ Updated Table 1–22, Table 1–29, Table 1–31, and Table 1–31.
December 2011	2.2	■ Added Table 2–31.
	2.2	■ Updated Table 2–28 and Table 2–34.
		 Added Table 2–2 and Table 2–21 and updated Table 2–5 with information about Stratix V GT devices.
November 2011	2.1	■ Updated Table 2–11, Table 2–13, Table 2–20, and Table 2–25.
		 Various edits throughout to fix SPRs.
May 2011		 Updated Table 2–4, Table 2–18, Table 2–19, Table 2–21, Table 2–22, Table 2–23, and Table 2–24.
	2.0	 Updated the "DQ Logic Block and Memory Output Clock Jitter Specifications" title.
		 Chapter moved to Volume 1.
		 Minor text edits.
		■ Updated Table 1–2, Table 1–4, Table 1–19, and Table 1–23.
December 2010	1.1	 Converted chapter to the new template.
		 Minor text edits.
July 2010	1.0	Initial release.